

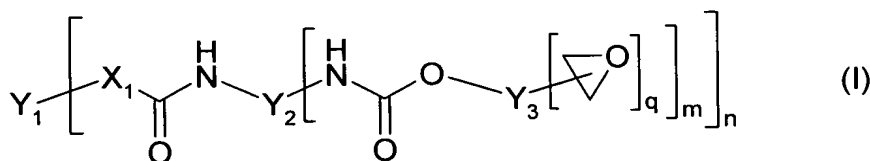
Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Withdrawn-Currently Amended) A composition comprising:

at least one epoxide adduct **A** having on average more than one epoxide group per molecule;

at least one polymer **B** of the formula (I)



wherein:

X_1 is O, S or NH;

Y_1 is ~~an n-valent radical of a reactive polymer after removal of the terminal amino, thiol or hydroxyl groups~~ a polyoxybutylene terminated with hydroxyl groups or a hydroxyl-terminated polybutadiene;

Y_2 is a divalent radical of aliphatic, cycloaliphatic, aromatic or araliphatic diisocyanates after removal of the isocyanate groups or is a trivalent radical of trimers or biurets of aliphatic, cycloaliphatic, aromatic or araliphatic diisocyanates after removal of the isocyanate groups;

Y_3 is a radical of an aliphatic, cycloaliphatic, aromatic or araliphatic epoxide containing a primary or secondary hydroxyl group after removal of the hydroxide and epoxide groups;

q is 2 or 3;

m is 1 or 2; and

n is 2, 3 or 4;

at least one thixotropic agent **C** based on a urea derivative in a non-diffusing carrier material; and

at least one hardening agent **D** for epoxy resins which is activated by elevated temperature.

2. (Withdrawn) The composition as claimed in claim 1, wherein the epoxide adduct **A** is obtainable from a reaction of at least one dicarboxylic acid and at least one diglycidyl ether; or

a reaction of at least one bis(aminophenyl) sulfone isomer or a reaction of at least one aromatic alcohol and at least one diglycidyl ether.

3. (Withdrawn) The composition as claimed in claim 2, wherein the dicarboxylic acid is a dimeric fatty acid and the diglycidyl ether is selected from the group consisting of bisphenol A diglycidyl ether, bisphenol F diglycidyl ether, and bisphenol A/F diglycidyl ether.

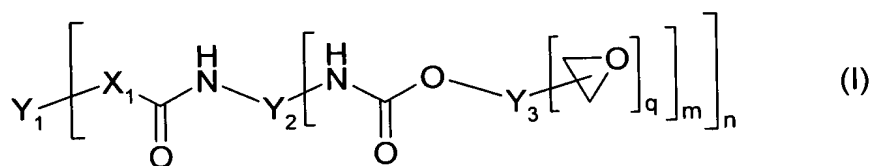
4. (Withdrawn) The composition as claimed in claim 2, wherein the aromatic alcohol is selected from the group consisting of 2,2-bis(4-hydroxyphenyl)propane, bis(4-hydroxyphenyl)methane, bis(4-hydroxyphenyl)sulfone, hydroquinone, resorcinol, pyrocatechol, naphthohydroquinone, naphthoresorcinol, dihydroxynaphthalene, dihydroxyanthraquinone, dihydroxybiphenyl, 3,3-bis(p-hydroxyphenyl)phthalides, 5,5-bis(4-hydroxyphenyl)hexahydro-4,7-methanoindane and all isomers of the abovementioned compounds and the diglycidyl ether is bisphenol A diglycidyl ether, bisphenol F diglycidyl ether and bisphenol A/F diglycidyl ether.

5. (Withdrawn) The composition as claimed in claim 1, wherein the polymer **B** is resilient.

6. (Withdrawn) The composition as claimed in claim 1, wherein the polymer **B** is soluble or dispersible in epoxy resins.

7. (Withdrawn) The composition as claimed in claim 1, wherein, in formula (I), n is 2 or 3.
8. (Canceled)
9. (Withdrawn) The composition as claimed in claim 1, wherein the polymer on which Y_1 in formula (I) is based is an OH equivalent weight of 600 - 6000 g/OH equivalent.
10. (Withdrawn) The composition as claimed in claim 1, wherein m is 1 and the diisocyanate on which Y_2 in formula (I) is based is HDI, IPDI, MDI or TDI.
11. (Withdrawn) The composition as claimed in claim 1, wherein the proportion by weight of all polymers **B** of the formula (I) is from 5 to 40% by weight based on a total weight of the composition.
12. (Withdrawn) The composition as claimed in claim 1, wherein the carrier material of the thixotropic agent **C** is a blocked polyurethane prepolymer.
13. (Withdrawn) The composition as claimed in claim 1, wherein the urea derivative in the thixotropic agent **C** is a product of a reaction of an aromatic monomeric diisocyanate with an aliphatic amine compound.
14. (Withdrawn) The composition as claimed in claim 1, wherein a proportion by weight of the thixotropic agent **C** is 5 - 40% by weight based on a total weight of the composition.
15. (Withdrawn) The composition as claimed in claim 14, wherein a proportion of the urea derivative is 5 - 50% by weight based on a weight of the thixotropic agent **C**.
16. (Withdrawn) The composition as claimed in claim 1, wherein the hardening agent **D** is a latent hardening agent selected from the group consisting of dicyandiamide, guanamines, guanidines and aminoguanidines.

17. (Withdrawn) The composition as claimed in claim 1, wherein a total proportion of the hardening agent **D** is 1 - 10% by weight based on a total weight of the composition.
18. (Withdrawn) The composition as claimed in claim 1, wherein at least one filler **E** is additionally present.
19. (Withdrawn) The composition as claimed in claim 18, wherein a total proportion of the filler **E** is 5 - 30% by weight based on a total weight of the total composition.
20. (Withdrawn) The composition as claimed in claim 1, wherein at least one reactive diluent **F** carrying epoxide groups is additionally present.
21. (Withdrawn) The composition as claimed in claim 1, wherein, after hardening, the composition has a low-temperature fracture energy, measured according to DIN 11343, of more than 10 J at 0°C.
22. (Currently Amended) An impact modifier terminated by epoxide groups of the formula (I)



wherein:

X_1 is O, S or NH;

Y_1 is a ~~n-valent radical of a reactive polymer after removal of the terminal~~
~~amine, thiol or hydroxyl groups~~ polyoxybutylene terminated with hydroxyl groups or a
hydroxyl-terminated polybutadiene;

Y_2 is a divalent radical of aliphatic, cycloaliphatic, aromatic or araliphatic diisocyanates after removal of the isocyanate groups or is a trivalent radical of trimers or biurets of aliphatic, cycloaliphatic, aromatic or araliphatic diisocyanates after removal of the isocyanate groups;

Y_3 is a radical of an aliphatic, cycloaliphatic, aromatic or araliphatic epoxide containing a primary or secondary hydroxyl group after removal of the hydroxide and epoxide groups;

q is 2 or 3;

m is 1 or 2;

n is 2, 3 or 4; and

the polymer on which Y_1 in formula (I) is based is a diol or triol having an OH equivalent weight of 600 - 6000 g/mol.

23-24. (Canceled)

25. (Previously Presented) A one-component thermally hardening epoxy resin adhesive comprising the impact modifier terminated by epoxide groups as claimed in claim 22.

26. (Previously Presented) A two-component epoxy resin adhesive comprising the impact modifier terminated by epoxide groups as claimed in claim 22.

27. (Withdrawn) A one-component adhesive comprising the composition as claimed in claim 1.

28. (Withdrawn) The one-component adhesive as claimed in claim 27, wherein the adhesive bonds heat-stable materials.

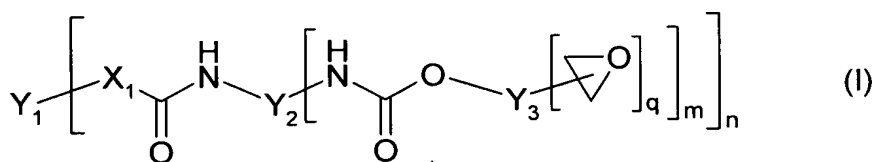
29. (Withdrawn) The one-component adhesive as claimed in claim 27, wherein the adhesive is an automotive body-shell construction adhesive.

30. (Withdrawn) A method for the adhesive bonding of heat-stable materials, wherein the heat-stable materials are brought into contact with a composition as claimed in claim 1 and comprises a hardening step at a temperature of 100 - 220°C.

31. (Withdrawn-Currently Amended) The method of claim 30, wherein the materials being brought into contact with the composition comprise:

at least one epoxide adduct **A** having on average more than one epoxide group per molecule;

at least one polymer **B** of the formula (I)



wherein:

X_1 is O, S or NH;

Y_1 is a polyoxybutylene terminated with hydroxyl groups or a hydroxyl-terminated polybutadiene ~~n-valent radical of a reactive polymer after removal of the terminal amino, thiol or hydroxyl groups;~~

Y_2 is a divalent radical of aliphatic, cycloaliphatic, aromatic or araliphatic diisocyanates after removal of the isocyanate groups;

or is a trivalent radical of trimers or biurets of aliphatic, cycloaliphatic, aromatic or araliphatic diisocyanates after removal of the isocyanate groups;

Y_3 is a radical of an aliphatic, cycloaliphatic, aromatic or araliphatic epoxide containing a primary or secondary hydroxyl group after removal of the hydroxide and epoxide groups;

q is 2 or 3;

m is 1 or 2; and

n is 2, 3 or 4;

at least one thixotropic agent **C** based on a urea derivative in a non-diffusing carrier material; and

at least one hardening agent **D** for epoxy resins which is activated by elevated temperature and the adhesively bonded materials being used at a temperature of from 100°C to -40°C.